

Product Change Notification - KSRA-03KOWN490

Date: 14 Aug 2017
Product Category: Memory
Notification subject: CCB 2983: Initial Notice: Qualification of 36.3K process technologies for selected products of the 24AAxx and 24LCxx device families available in 8L UDFN package.
Notification text: **PCN Status:**
 Initial notification.

Microchip Parts Affected:

Please open the attachments found in the attachments field below labeled as PCN_#_Affected_CPN.

NOTE: For your convenience Microchip includes identical files in two formats (.pdf and .xls).

Description of Change:

Qualification of 36.3K process technology for selected products of the 24AAxx and 24LCxx device families available in 8L TDFN package.

Pre Change:

Available in 160K wafer technology fabricated at Microchip fabrication sites FAB2 and FAB4 (Tempe, AZ and Gresham, OR, USA) using 8 inch wafers

Post Change:

Available in 160K wafer technology fabricated at Microchip fabrication sites FAB2 and FAB4 (Tempe, AZ and Gresham, OR, USA) using 8 inch wafers or available in 36.3K wafer technologies fabricated at FAB 5 (Colorado Springs, CO, USA) using 6 inch wafers

Pre and Post Change Summary:

	Pre Change	Post Change	
Wafer Technology	160K wafer technology	160K wafer technology	36.3K wafer technology
Fabrication Location	Microchip Fabrication Sites FAB 2 and FAB4 (Tempe, AZ and Gresham, OR, USA)	Microchip Fabrication Sites FAB 2 and FAB4 (Tempe, AZ and Gresham, OR, USA)	FAB 5 (Colorado Springs, CO USA)
Wafer Diameter	8 inches (200 mm)	8 inches (200 mm)	6 inches (150 mm)
Quality certification	ISO/TS16949	ISO/TS16949	ISO9001/TS16949

Impacts to Data Sheet:

None

Change Impact:

None

Reason for Change:

To improve manufacturability by qualifying an additional fabrication site.

Change Implementation Status:

In Progress

Estimated Qualification Completion Date:

August 2017

Note: Please be advised the qualification completion times may be extended because of unforeseen business conditions however implementation will not occur until after qualification has completed and a final PCN has been issued. The final PCN will include the qualification report and estimated first ship date. Also note that after the estimated first ship date guided in the final PCN customers may receive pre and post change parts.

Time Table Summary:

	August 2017				
Workweek	31	32	33	34	35
Initial PCN Issue Date			X		
Qual Report Availability					X
Final PCN Issue Date					X

Method to Identify Change:

Traceability code

Qualification Plan:

Please open the attachments included with this PCN labeled as PCN_#_Qual Plan.

Revision History:

August 14, 2017: Issued initial notification.

The change described in this PCN does not alter Microchip's current regulatory compliance regarding the material content of the applicable products.

Attachment(s):

[PCN_KSRA-03KOWN490_Affected CPN.pdf](#)
[PCN_KSRA-03KOWN490_Qual Plan.pdf](#)
[PCN_KSRA-03KOWN490_Affected CPN.xlsx](#)

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Affected Catalog Part Numbers (CPN)

PCN_KSRA-03KOWN490
CATALOG_PART_NBR
24AA01HT-I/MNY
24AA01T-I/MNY
24AA02HT-I/MNY
24AA02T-I/MNY
24AA04HT-I/MNY
24AA04T-I/MNY
24LC01BHT-I/MNY
24LC01BT-I/MNY
24LC02BHT-I/MNY
24LC02BT-I/MNY
24LC04BHT-I/MNY
24LC04BT-I/MNY